Preferred Device

Switching Transistor

NPN Silicon

Features

• Pb-Free Package is Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CEO}	40	Vdc
Collector - Base Voltage	V_{CBO}	60	Vdc
Emitter-Base Voltage	V_{EBO}	6.0	Vdc
Collector Current – Continuous	I _C	600	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C	P _D	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2)	P _D	300	mW
T _A = 25°C Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

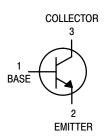
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



ON Semiconductor®

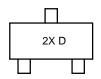
http://onsemi.com





SOT-23 (TO-236) CASE 318-08 STYLE 6

MARKING DIAGRAM



2X = Specific Device Code D = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS				1	1
Collector – Emitter Breakdown Voltage (Not (I _C = 1.0 mAdc, I _B = 0)	V _{(BR)CEO}	40	_	Vdc	
Collector – Base Breakdown Voltage (I _C = 0.1 mAdc, I _E = 0)	V _{(BR)CBO}	60	_	Vdc	
Emitter – Base Breakdown Voltage $(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	6.0	_	Vdc	
Base Cutoff Current (V _{CE} = 35 Vdc, V _{EB} = 0.4 Vdc)	I _{BEV}	1	0.1	μAdc	
Collector Cutoff Current (V _{CE} = 35 Vdc, V _{EB} = 0.4 Vdc)				0.1	μAdc
ON CHARACTERISTICS (Note 3)			•	-	-
DC Current Gain $ \begin{aligned} &(I_C = 0.1 \text{ mAdc, V}_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 1.0 \text{ mAdc, V}_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 10 \text{ mAdc, V}_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 150 \text{ mAdc, V}_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 500 \text{ mAdc, V}_{CE} = 2.0 \text{ Vdc}) \end{aligned} $		h _{FE}	20 40 80 100 40	- - - 300 -	-
Collector – Emitter Saturation Voltage (I _C = 150 mAdc, I _B = 15 mAdc) (I _C = 500 mAdc, I _B = 50 mAdc)		V _{CE(sat)}		0.4 0.75	Vdc
Base – Emitter Saturation Voltage ($I_C = 150 \text{ mAdc}$, $I_B = 15 \text{ mAdc}$) ($I_C = 500 \text{ mAdc}$, $I_B = 50 \text{ mAdc}$)	V _{BE(sat)}	0.75 -	0.95 1.2	Vdc	
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain — Bandwidth Product (I _C = 20 mAdc, V _{CE} = 10 Vdc, f = 100 MH	łz)	f _T	250	_	MHz
Collector–Base Capacitance (V _{CB} = 5.0 Vdc, I _E = 0, f = 1.0 MHz)		C _{cb}	1	6.5	pF
Emitter–Base Capacitance $(V_{EB} = 0.5 \text{ Vdc}, I_{C} = 0, f = 1.0 \text{ MHz})$		C _{eb}	1	30	pF
Input Impedance (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz)		h _{ie}	1.0	15	kΩ
Voltage Feedback Ratio $(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$		h _{re}	0.1	8.0	X 10 ⁻⁴
Small – Signal Current Gain $(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$		h _{fe}	40	500	_
Output Admittance (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz)		h _{oe}	1.0	30	μmhos
SWITCHING CHARACTERISTICS					
Delay Time	(V _{CC} = 30 Vdc, V _{EB} = 2.0 Vdc,	t _d	_	15	
Rise Time	I _C = 150 mAdc, I _{B1} = 15 mAdc)	t _r	_	20	ns
Storage Time	$(V_{CC} = 30 \text{ Vdc}, I_{C} = 150 \text{ mAdc},$	t _s	_	225	ne
Fall Time	I _{B1} = I _{B2} = 15 mAdc)	t _f	ı	30	ns

^{3.} Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT4401LT1	SOT-23 (TO-236)	3000 Tape & Reel
MMBT4401LT1G	SOT-23 (TO-236) (Pb-Free)	3000 Tape & Reel
MMBT4401LT3	SOT-23 (TO-236)	10,000 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

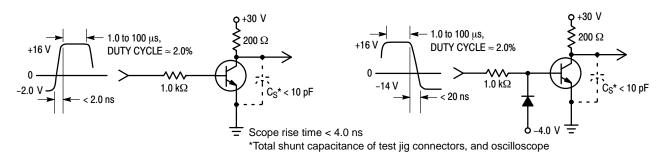
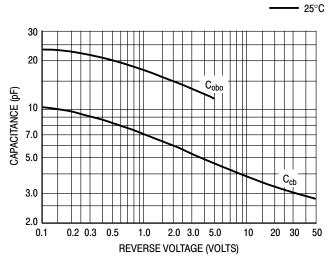


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

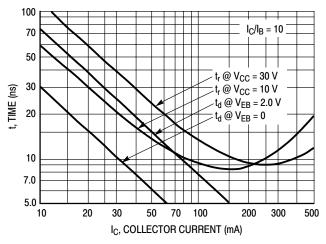
TRANSIENT CHARACTERISTICS



—— 100°C 10 7.0 V_{CC} = 30 V 5.0 $I_C/I_B = 10$ 3.0 2.0 Q, CHARGE (nC) 1.0 0.7 0.5 0.3 0.2 10 20 70 100 200 300 50 500 I_C, COLLECTOR CURRENT (mA)

Figure 3. Capacitances

Figure 4. Charge Data



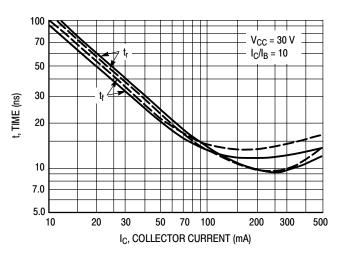
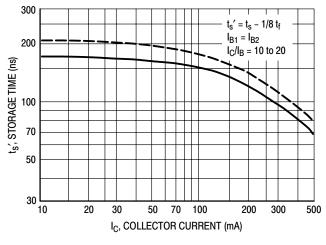


Figure 5. Turn-On Time

Figure 6. Rise and Fall Times



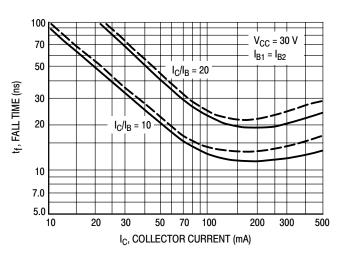


Figure 7. Storage Time

Figure 8. Fall Time

SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE} = 10 \text{ Vdc}$, $T_A = 25^{\circ}\text{C}$; Bandwidth = 1.0 Hz

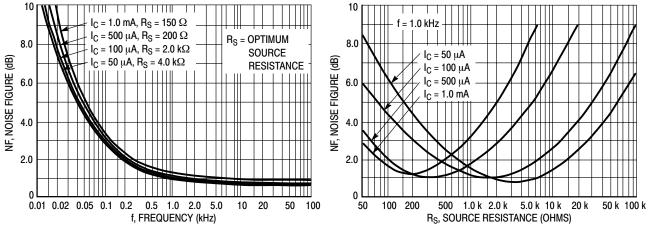


Figure 9. Frequency Effects

Figure 10. Source Resistance Effects

h PARAMETERS

 $V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C}$

This group of graphs illustrates the relationship between h_{fe} and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were selected from the MMBT4401LT1 lines, and the same units were used to develop the correspondingly numbered curves on each graph.

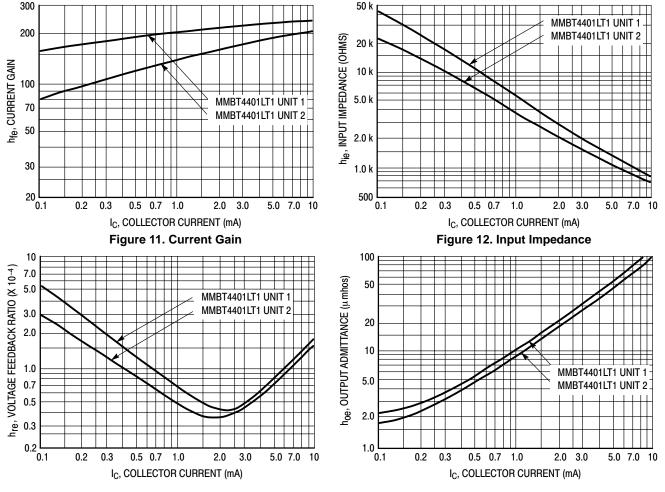


Figure 13. Voltage Feedback Ratio

Figure 14. Output Admittance

STATIC CHARACTERISTICS

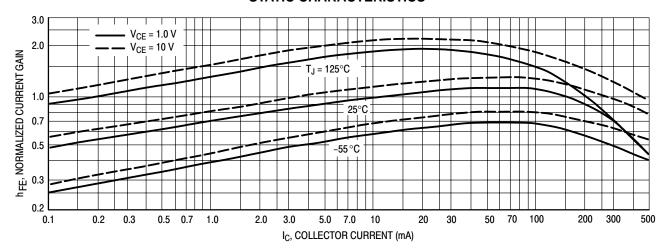


Figure 15. DC Current Gain

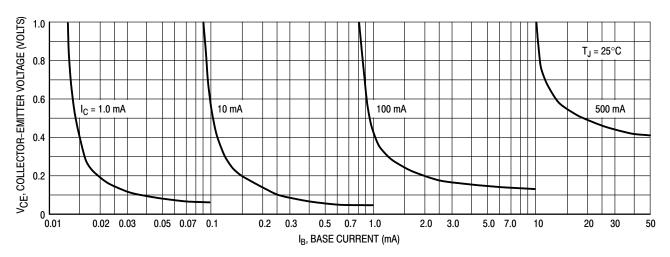


Figure 16. Collector Saturation Region

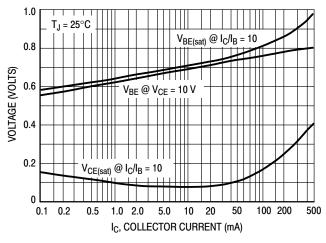


Figure 17. "On" Voltages

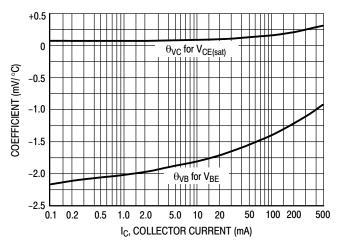
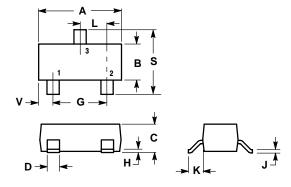


Figure 18. Temperature Coefficients

PACKAGE DIMENSIONS

CASE 318-08 SOT-23 (TO-236) **ISSUE AH**



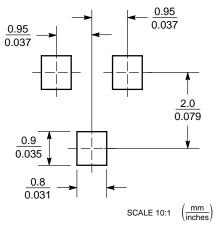
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATEDIAL
- MATERIAL.
 4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
٧	0.0177	0.0236	0.45	0.60

- STYLE 6:
 PIN 1. BASE
 2. EMITTER
 3. COLLECTOR

SOLDERING FOOTPRINT*



SOT-23

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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